

Serial No.: 10/074,840

**REMARKS**

No new matter has been added. The Applicant again requests entry of the amendments as set forth in the Appendices hereto prior to examination of the application on the merits.

Respectfully submitted,



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**VERSION OF CLAIMS WITH MARKINGS TO SHOW CHANGES MADE**

2. (Amended) The method of claim 1, further comprising storing data including at least one physical parameter of said at least one semiconductor device and of said substantially hermetic package in computer memory, and using the stored data in conjunction with a machine vision system to recognize a location and orientation of at least one of said at least one semiconductor device and said surface thereof.

7. (Amended) The method of claim 6, wherein said securing said at least one additional layer to said previously formed layer of said substantially hermetic package comprises substantially encapsulating said at least one semiconductor device.

10. (Amended) The method of claim 9, wherein said stereolithographically fabricating further comprises:  
providing at least one additional sheet of hermetic packaging material; and  
defining at least boundaries of an additional, corresponding layer of the substantially hermetic package in said at least one additional sheet.

24. (Amended) The method of claim 22, further comprising:  
exposing at least one bond pad on [said]an active surface of at least one of said plurality of substantially hermetically packaged semiconductor dice.

25. (Amended) The method of claim 24, wherein said exposing comprises etching a region of [said]an at least partially consolidated hermetic packaging material located above said at least one bond pad.